

*Ain Shams University
Faculty of Education
Physics Department*

***Effect of adding nano-sized particles on
thermal, structural and mechanical properties
of some Sn-Ag-Cu-based solder alloys***

Thesis

***Submitted for the Degree of Ph.D. Teacher's Preparation in
Science (Physics)***

By

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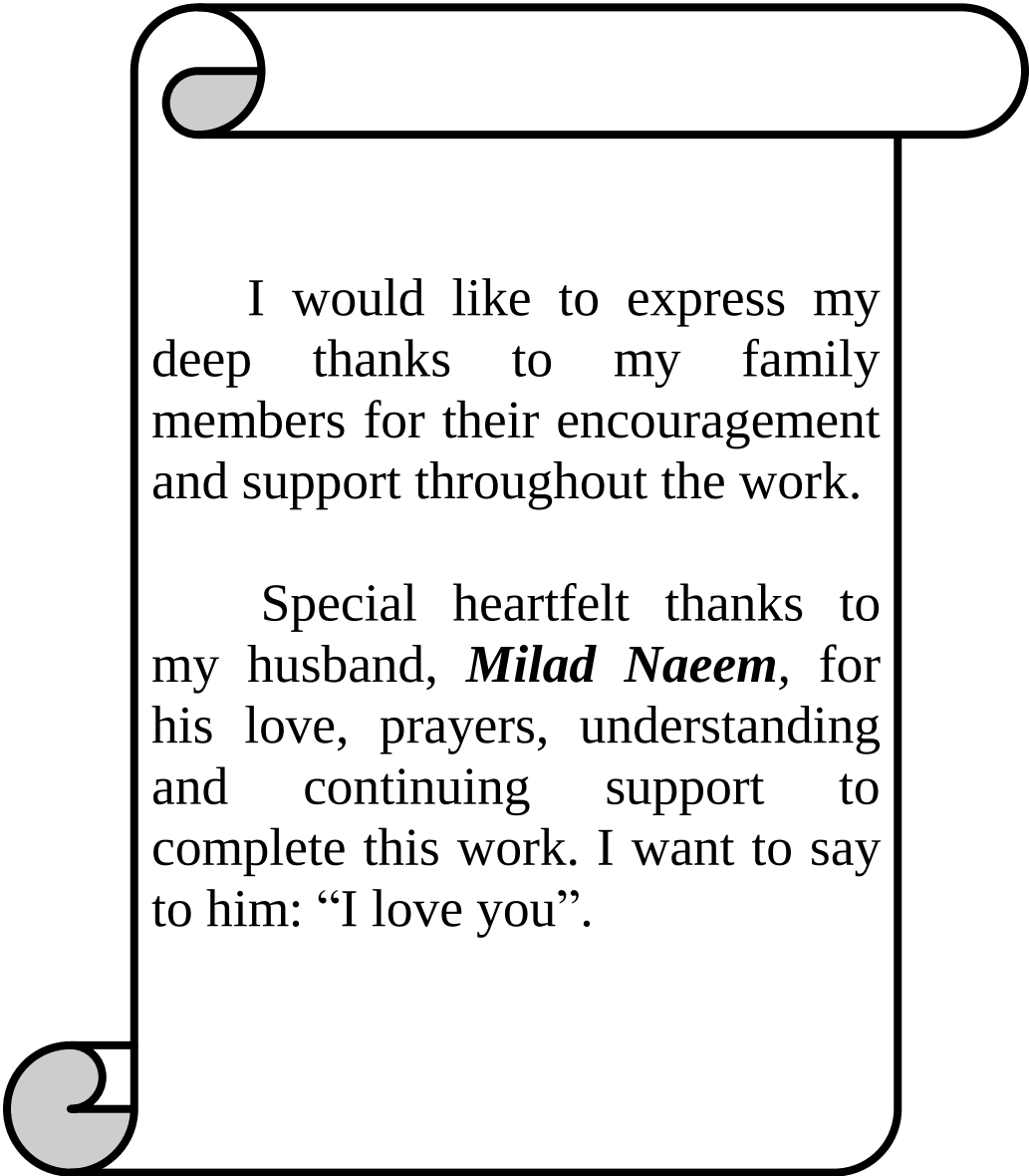
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Contents

Contents

Page

List of figures.....	a
List of tables.....	j
List of equations	k
Abstract.....	l
Summary.....	m
Published paper.....	p

CHAPTER 1

Introduction and Literature Review

1-1	Deformation fundamentals.....	1
	Point defects	1
	Line defects (dislocations)	1
	Surface/planar defects	2
	Volume defects	3
1-2	Elastic properties of dislocations	3
1-3	Dislocation motion	4
1-4	Dislocation interactions	5
1-5	Multiplication of dislocations	5
1-6	Work-hardening of metals and alloys.....	6
1-7	Mechanisms of work-hardening	7
	Strain-hardening.....	7
	Matrix strengthening.....	7
	Grain boundary hardening.....	8
	Grain size effect.....	8
	Precipitation or dispersion strengthening.....	9
1-8	Soldering alloys.....	10

	<i>page</i>
1-9 Sn-Ag-Cu (SAC) phase diagram.....	12
1-10 Sn - Ag - Cu solder alloy.....	13
1-11 Applications of Sn-Ag-Cu solder alloy.....	15
1-12 Composite solder alloys	17
1-13 Graphene Oxide Nano Sheets (GONSs).....	17
1-14 Mechanical properties of metals and alloys....	20
Stress-strain characteristics.....	20
Factors affecting the stress-strain curve	25
Creep characteristics	27
Factors affecting the creep curve.....	30
Mechanisms of creep.....	34
1-15 Literature review.....	37
Sn-Ag-Cu solder alloys.....	37
Sn-Ag-Cu solder alloys with nanoparticles additions (composite solders).....	47
Addition of Graphene Nano-Sheets.....	51
1-16 Scope and Outline of the Present Work.....	54

CHAPTER 2

Experimental Techniques and Devices

2-1 Samples preparation.....	55
2-2 Heat treatments	56
2-3 The components of the mechanical system....	56
Tensile-testing machine.....	56
Measurement technique (tensile test).....	60
2-4 X-ray diffraction (XRD).....	64
2-5 Scanning electron microscope (SEM) and energy dispersive spectroscopy (EDS) techniques.....	64

	<i>Page</i>
2-6 Differential scanning calorimeter (DSC) technique	67

CHAPTER 3

Results and Discussions

3-1 Microstructure evolutions and thermal analysis of SAC105, SAC105–1wt%Zn and SAC105–1wt%Zn–0.2wt%GONSs solder alloys	69
3-1-1 Microstructure analysis	69
3-1-2 Melting characteristics.....	74
3-1-3 Role of Zn element in the mechanical response of the SAC105 solder alloy.....	78
3-1-4 Effect of GONSs on the microstructure and mechanical response of the SAC105 solder alloy	79
3-2 Tensile stress-strain characteristics of plain SAC105, SAC105-Zn containing and SAC105-Zn composite solder alloys.....	82
3-2-1 Effect of strain rate and testing temperature on the stress-strain characteristics of the three solder alloys	82
3-2-2 Effect of structure on the stress-strain characteristics	83
3-2-3 Influence of strain rate and temperature on the stress-strain parameters.....	83
3-2-4 Influence of structure on the stress-strain parameters.....	91
3-2-5 Stress exponent.....	99
3-2-6 The work-hardening coefficient, χ_p	101

	<i>Page</i>
3-2-7 The activation energy of the deformation process.....	104
3-3 Relaxation in plain SAC105, SAC105-Zn containing and SAC105-Zn-GONSs composite solder alloys.....	106
3-3-1 Stress relaxation rate.	107
3-3-2 Critical relaxed stress.....	113
3-3-3 Activation energy.....	116
3-4 Tensile creep characteristics of SAC105 plain, SAC105-Zn containing and SAC105-Zn-GONSs composite solder alloys.....	118
3-4-1 Steady state creep.....	126
3-4-2 Stress dependence of rupture time.....	133
3-4-3 Energy activating creep process.....	139
Conclusions	142
References	144
Arabic summary	

List of figures

List of figures

<i>Figure</i>	<i>Caption</i>	<i>Page</i>
Figure 1:	Melting points of different lead-free solder additives.....	12
Figure 2:	Phase diagram of SnAgCu (SAC) alloy.....	13
Figure 3:	The market share of different Pb-free solders.....	15
Figure 4:	Graphene is an atomic-scale honeycomb lattice made of carbon atoms.....	19
Figure 5:	A typical stress-strain curve.....	21
Figure 6:	Tensile stress-strain curves for metals...	23
Figure 7:	Creep curve under constant stress and temperature.....	28
Figure 8:	Effect of stress and temperature on strain-time creep curves.....	31
Figure 9:	Creep deformation map.....	35
Figure 10:	Schematic diagram of the mechanical system.....	58
Figure 11:	The force sensor.....	59
Figure 12:	The rotary motion sensor.....	59
Figure 13:	The science workshop 500 interface.....	59
Figure 14:	Stress-strain relationship as obtained by the data studio graph.....	61

<i>Figure</i>	<i>Caption</i>	<i>Page</i>
Figure 15:	Creep curve as obtained by the data studio graph.....	63
Figure 16:	Schematic representation of a stress-relaxation curve as obtained by the data studio graph.....	63
Figure 17:	Philips X' Pert multipurpose diffraction diffractometer.....	65
Figure 18:	JEOL, JSM-5400 scanning electron microscope.....	66
Figure 19:	The typical DSC traces.....	67
Figure 20:	(a) XRD pattern for GONSs, (b) bright field transmission electron microscope for GONSs and (c) bright field transmission electron microscope of magnified part of GONSs.....	69
Figure 21:	XRD pattern for (a) SAC105 and (b) SAC105-Zn solder alloys, and (c) SAC105-Zn-GONSs composite solder...	71
Figure 22:	Optical micrographs showing the IMCs and β -Sn in (a) SAC105 and (b) SAC105-Zn solder alloys, and (c) SAC105-Zn-GONSs composite solder...	72
Figure 23:	EDS for (a) SAC105 and (b) SAC105-Zn-GONSs solders.	73

Figure	Caption	Page
Figure 24:	SEM micrographs showing the IMCs for (a) SAC105, (b) magnified part from (a) and the corresponding EDS curves...	75
Figure 25:	DSC curves of: (a) SAC105 plain, (b) SAC105–Zn and (c) SAC105–Zn-GONSs composite solder.....	76
Figure 26:	Stress-strain curves for SAC105, SAC105-Zn and SAC105-Zn-GONSs samples aged at 400 K for 30 minutes and tested at different strain rates and different testing temperatures as indicated.....	84
Figure 27:	Stress-strain curves for SAC105, SAC105–Zn and SAC105–Zn-GONSs solder alloys tested at different strain rates and testing temperatures as indicated.....	85
Figure 28:	Testing temperature (T_l) dependence of (a) Young's modulus Y and (b) yield stress σ_y for SAC105 plain, SAC105–Zn containing and (c) SAC105-Zn composite samples at different strain rates.....	88